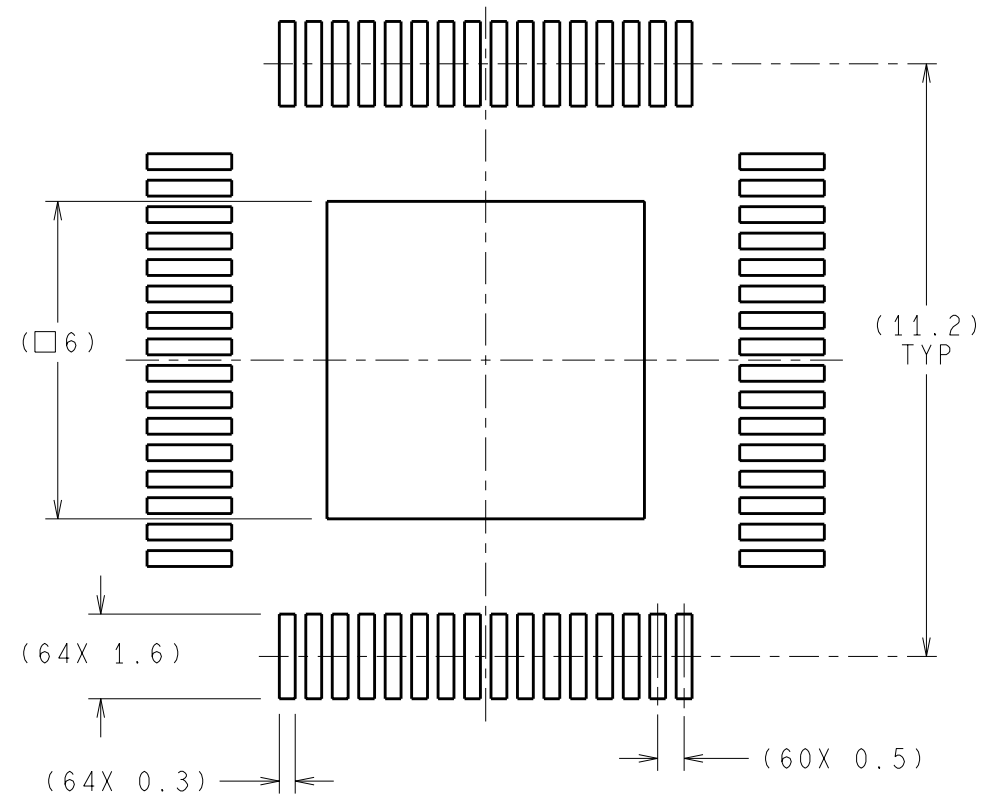
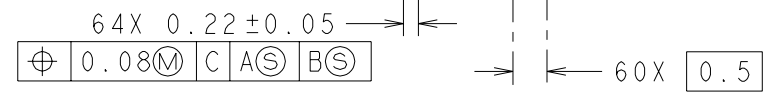
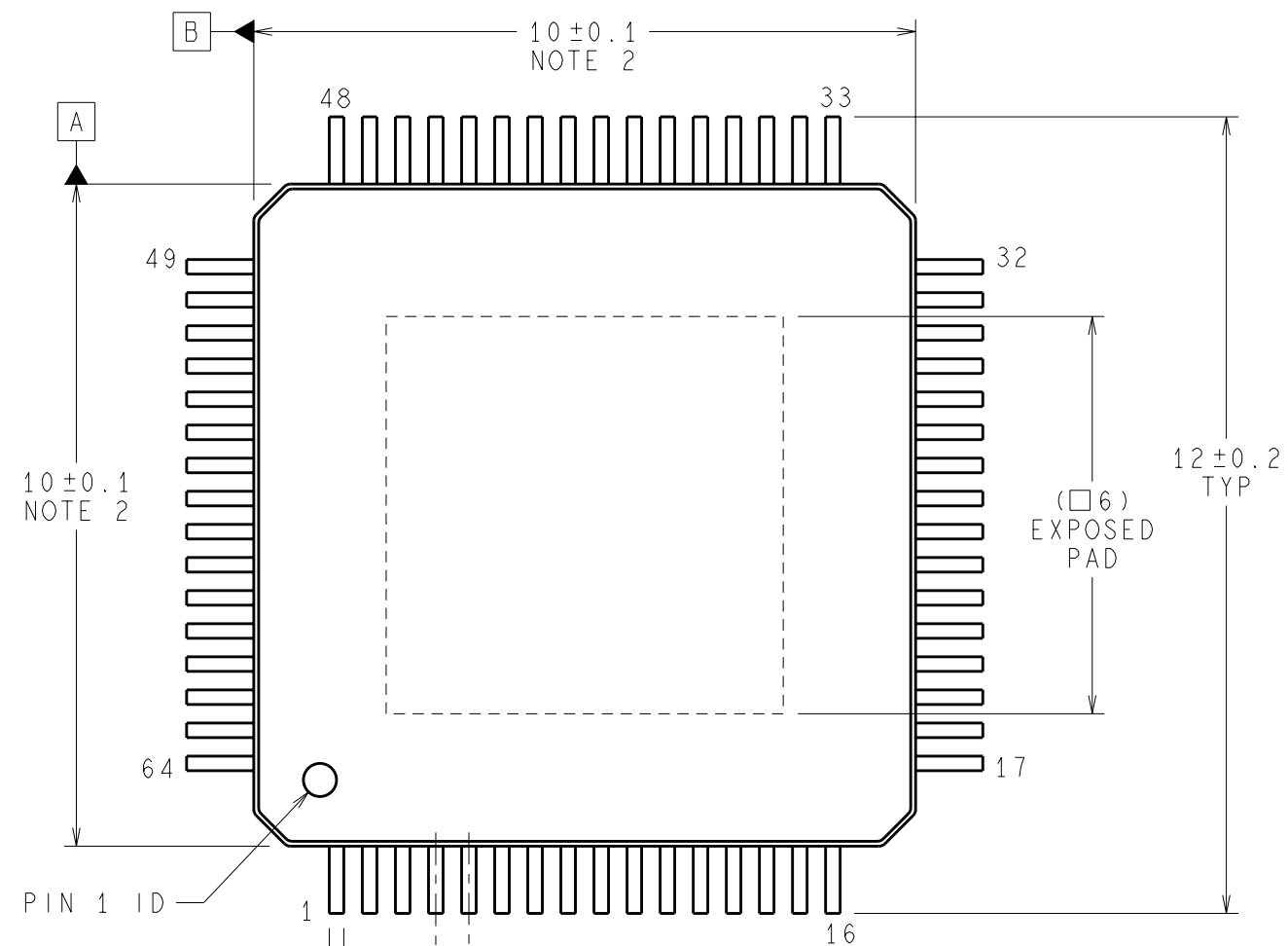
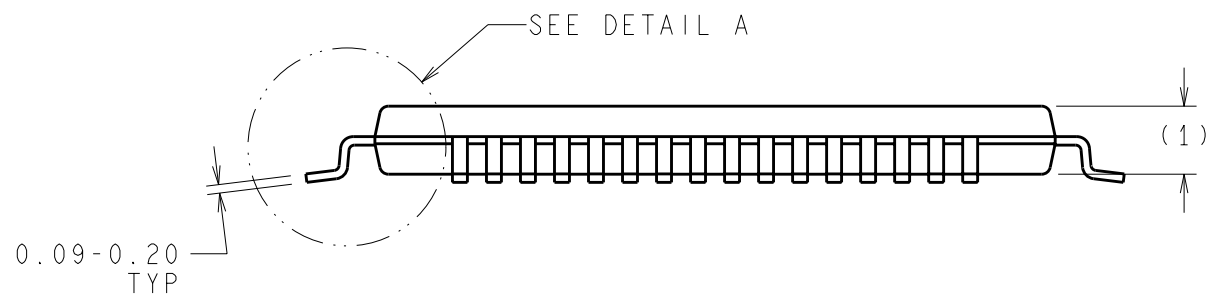


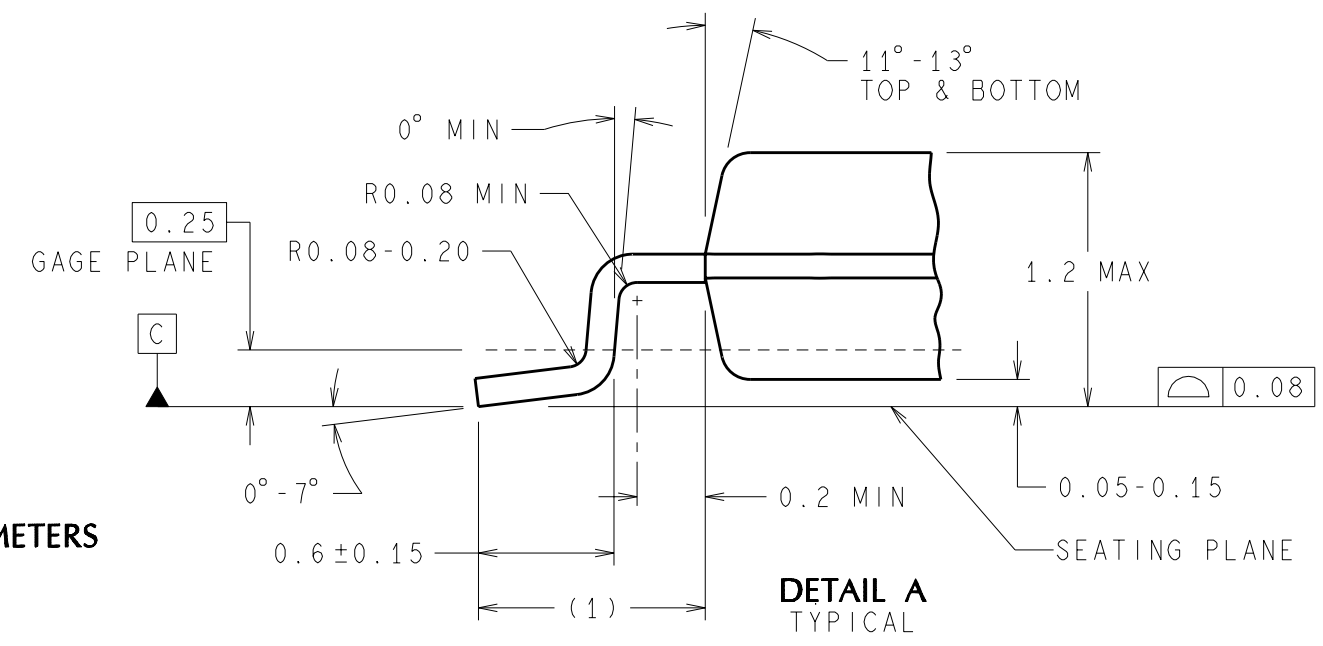
REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	1499	05/28/2004	TL/RW



LAND PATTERN RECOMMENDATION



DIMENSIONS ARE IN MILLIMETERS



NOTES: UNLESS OTHERWISE SPECIFIED

1. FOR LEAD FINISH THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE ([www.national.com](http://www.national.com)).
2. DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. MAXIMUM ALLOWABLE MOLD PROTRUSION 0.25mm PER SIDE.
3. REFERENCE JEDEC REGISTRATION MS-026, VARIATION ACD.

APPROVALS		DATE	 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090	
DRAWN	T. LEQUANG	05/28/2004		
DFTG. CHK.	MARTA SUCHY	05/28/2004		
ENGR. CHK.	RANDY WALBERG	05/28/2004		
TQFP, 10x10x1mm, 64 LEAD, 0.5mm PITCH, EXPOSED PAD				
PROJECTION	SCALE	SIZE	DRAWING NUMBER	REV
 MM	NTS	B	(SC)MKT-VXE64A	A
FORMERLY: N/A			SHEET 1 of 1	